



Material Content Data Sheet



Sales Product Name		BTS50055-1TMC		Issued		29. August 2013		
MA#		MA000907914						
Package		PG-TO220-7-4		Weight*		1531.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.514	1.01	1.01	10132	10132
leadframe	non noble metal	iron	7439-89-6	0.910	0.06		594	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		178	
	non noble metal	copper	7440-50-8	909.052	59.37	59.45	593681	594454
wire	non noble metal	aluminium	7429-90-5	6.713	0.44	0.44	4384	4384
encapsulation	organic material	carbon black	1333-86-4	8.672	0.57		5663	
	plastics	epoxy resin	-	95.389	6.23		62297	
	inorganic material	silicondioxide	60676-86-0	474.056	30.96	37.76	309596	377556
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7896	7896
plating	non noble metal	nickel	7440-02-0	0.216	0.01		141	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	141
glue	plastics	Polyimide	26023-21-2	0.217	0.01	0.01	142	142
solder	noble metal	silver	7440-22-4	0.203	0.01		132	
	non noble metal	tin	7440-31-5	0.162	0.01		106	
	non noble metal	lead	7439-92-1	7.743	0.51	0.53	5057	5295
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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